Attorney's Docket No.:	
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## DECLARATION, POWER OF ATTORNEY AND PETITION

I (We), the undersigned inventor(s), hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I (We) believe that I am (we are) the original, first, and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SOLUTION FOR SUBSTRATE SPOTTING AND SPOTTING METHOD

he specification of which	
is attached hereto.	
was filed on	a
Application Serial No.	
and amended on	
was filed as PCT international application	
Number	
on	,
and was amended under PCT Article 19	
o n	(if applicable).

I (We) hereby state that I (We) have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above; that I (We) do not know and do not believe that this invention was ever known or used before my invention or discovery thereof, or patented or described in any printed publication in any country before my invention or discovery thereof, or more than one year prior to this application, or in public use or on sale in the United States for more than one year prior to this application; that this invention or discovery has not been patented or made the subject of an inventor's certificate in any country foreign to the United States on an application filed by me or my legal representatives or assigns more than twelve months before this application.

I (We) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

I (We) hereby claim foreign priority benefits under Section 119(a)-(d) of Title 35 United States Code, of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

			Priori	t y	
Application N	lo. Country	Filing date	claime	ed	
2002-187711	Japan	June 27, 2002	■ Yes	□ No	
			☐ Yes	□ No	
			☐ Yes	□ No	
			☐ Yes	□ No	
of any United	States application(	s) listed below.			
(Application	Number)	(Filing Date	)		
(Application	Number)	(Filing Date	)	<del></del>	

I (We) hereby claim the benefit under Section 120 of Title 35 United States Code, of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Section 112 of Title 35 United States Code, I (We) acknowledge the duty to disclose material information as defined in Section 1.56(a) of Title 37 Code of Federal Regulations, which occurred between the filing date of the prior application and national or PCT international filing date of this application:

		Status (pending,
		patented,
Application Serial No.	Filing Date	abandoned)
<u> </u>		
And I (We) hereby appoint	Stanley P. Fisher, Registration	on No. 24,344 and Juan Carlos
Marquez, Registration No. 34,072.		
I(We) hereby request that all corr	espondence regarding this ap	oplication be sent to the firm of Reed
Smith Hazel & Thomas LLP whose	Post office address is: 3110 F	Fairview Park Drive, Suite 1400, Falls
Church, Virginia 22042-4503 U.S.	Α.	
		erein of my (our) knowledge
are true and that all state	ments were made with	the knowledge that willful
		le by fine or imprisonment,
or both, under Section 100	01 of Title 18 of the Uni	ted States Code and that such
willful false statements m	ay jeopardize the validi	ity of the application or any
patent issued thereon.		
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Date	
	Residence:
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Date	